

### SGM48523C/SGM48524C Dual 5A, High-Speed, Low-Side Gate Drivers with Negative Input Voltage Capability

#### GENERAL DESCRIPTION

The SGM48523C and SGM48524C are dual highspeed low-side gate drivers for power switches. They have rail-to-rail driving capability and can sink or source up to 5A peak current with capacitive loads. The propagation delays are very short and well matched between the two channels that make the device well suited for applications that need accurate dual gate driving such as synchronous rectifiers. The matched propagation delays also allow for paralleling the two channels when higher driving current is required for example for paralleled switches. The input voltage thresholds are fixed, independent of supply voltage (V<sub>DD</sub>), and compatible with low voltage TTL and CMOS logic. Noise immunity is excellent due to the wide hysteresis window between the input low and high thresholds. The devices have internal pull-up/pull-down resistors on the input pins to ensure low state on the driver output when the input is floating.

The dual inverting SGM48523C and the dual non-inverting SGM48524C are both available in Green SOIC-8, TDFN-3×3-8L and MSOP-8 (Exposed Pad) packages.

#### **APPLICATIONS**

DC/DC Converters

Solar Power, Motor Drivers

Switched-Mode Power Supplies

Gate Drive for Emerging Wide Bandgap Devices

#### **FEATURES**

- Two Independent Gate Drive Channels
- 5A Source and 5A Sink Peak Currents
- Wide Supply Voltage Range: 8.5V to 18V
- TTL and CMOS Compatible Logic Threshold
- Logic Levels Independent of Supply Voltage
- Hysteretic Input Logic for High Noise Immunity
- Outputs Held Low when Inputs are Floating
- Fast Propagation Delays
- Fast Rise Time: 7ns (TYP)
- Fast Fall Time: 7ns (TYP)
- Ringing Suppression
- Negative Voltage Capability on INx Pins:
  - -10V when  $(V_{DD} V_{INx}) \le 20V$
- Negative Voltage Capability on ENx Pins:
  - -10V when  $(V_{DD} V_{ENx}) \le 20V$
- Negative Voltage Capability on OUTx Pin:
  - -2V (Pulse < 200ns)
- Protection Features
  - Thermal Shutdown Protection
  - Under-Voltage Lockout
- -40℃ to +125℃ Operating Temperature Range
- Available in Green SOIC-8, MSOP-8 (Exposed Pad) and TDFN-3×3-8L Packages

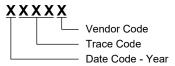


#### PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
	SOIC-8	-40°C to +125°C	SGM48523CXS8G/TR	SGM 48523CXS8 XXXXX	Tape and Reel, 4000
SGM48523C	MSOP-8 (Exposed Pad)	-40°C to +125°C	SGM48523CXPMS8G/TR	SGM03G XPMS8 XXXXX	Tape and Reel, 4000
	TDFN-3×3-8L	-40°C to +125°C	SGM48523CXTDB8G/TR	SGM 03DDB XXXXX	Tape and Reel, 4000
SGM48524C	SOIC-8	-40°C to +125°C	SGM48524CXS8G/TR	SGM 48524CXS8 XXXXX	Tape and Reel, 4000
	MSOP-8 (Exposed Pad)	-40°C to +125°C	SGM48524CXPMS8G/TR	SGM03E XPMS8 XXXXX	Tape and Reel, 4000
	TDFN-3×3-8L	-40°C to +125°C	SGM48524CXTDB8G/TR	SGM 03BDB XXXXX	Tape and Reel, 4000

#### MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

#### ABSOLUTE MAXIMUM RATINGS

VDD0.3V to 20V
Continuous INA, INB when (V <sub>DD</sub> - V <sub>INx</sub> ) ≤ 20V
-10V to V <sub>DD</sub> + 0.3V
Continuous ENA, ENB when $(V_{DD} - V_{ENx}) \le 20V$
-10V to V <sub>DD</sub> + 0.3V
Continuous OUTA, OUTB (DC)0.3V to $V_{DD}$ + 0.3V
Pulse OUTA, OUTB (Pulse < 200ns)2V to $V_{DD}$ + 0.3V
Package Thermal Resistance
SOIC-8, θ <sub>JA</sub> 121°C/W
MSOP-8 (Exposed Pad), θ <sub>JA</sub> 55°C/W
TDFN-3×3-8L, θ <sub>JA</sub>
Junction Temperature+150°C
Storage Temperature Range65°C to +150°C
Lead Temperature (Soldering, 10s)+260°C
ESD Susceptibility
HBM7000V
CDM1000V

#### RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range	8.5V to 18V
Operating Junction Temperature Range	40°C to +125°C

#### **OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

#### **ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

#### **DISCLAIMER**

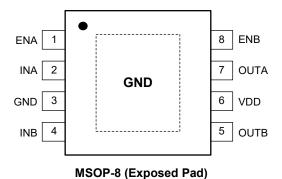
SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

#### **PIN CONFIGURATIONS**

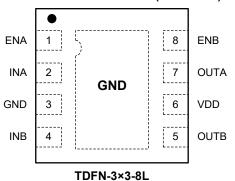
# SGM48523C (TOP VIEW) ENA 1 INA 2 GND 3 INB 4 SOIC-8

# SGM48524C (TOP VIEW) ENA 1 INA 2 GND 3 INB 4 SOIC-8

#### **SGM48523C/SGM48524C (TOP VIEW)**



#### **SGM48523C/SGM48524C (TOP VIEW)**

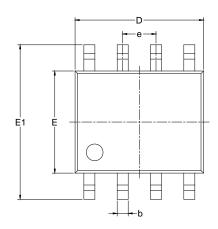


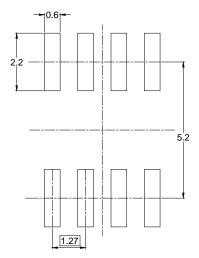
#### PIN DESCRIPTION

PIN	NAME	I/O	FUNCTION
1	ENA	I	Channel A Enable Input. Pull ENA high or leave it floating to enable OUTA output. Pull ENA low to disable OUTA output, ignoring INA state.
2	INA	Ι	Input for Channel A. Inverting input in SGM48523C and non-inverting input in SGM48524C. OUTA is held low if INA is unbiased or left floating.
3	GND	_	Ground. Reference pin for all signals.
4	INB	I	Input for Channel B. Inverting input in SGM48523C and non-inverting input in SGM48524C. OUTB is held low if INB is unbiased or left floating.
5	OUTB	0	Channel B Output.
6	VDD	ı	Power Supply Input.
7	OUTA	0	Channel A Output.
8	ENB	I	Channel B Enable Input. Pull ENB high or leave it floating to enable OUTB output. Pull ENB low to disable OUTB output, ignoring INB state.
Exposed Pad	GND	_	Exposed Pad. It is internally connected to GND. Connect it to a large ground plane to maximize thermal performance; not intended as an electrical connection point.

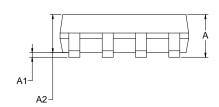
NOTE: I: input, O: output.

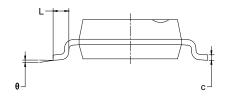
# **PACKAGE OUTLINE DIMENSIONS SOIC-8**





RECOMMENDED LAND PATTERN (Unit: mm)



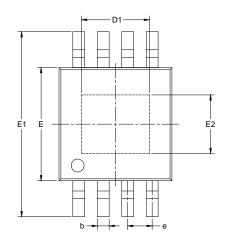


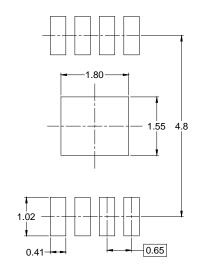
Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.27 BSC		0.050	BSC	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

- Body dimensions do not include mode flash or protrusion.
   This drawing is subject to change without notice.

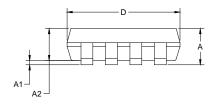
# **PACKAGE OUTLINE DIMENSIONS**

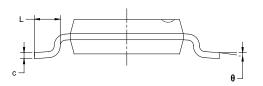
### MSOP-8 (Exposed Pad)





RECOMMENDED LAND PATTERN (Unit: mm)



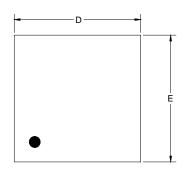


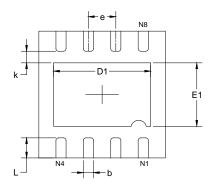
Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
Α	0.820	1.100	0.032	0.043	
A1	0.020	0.150	0.001	0.006	
A2	0.750	0.950	0.030	0.037	
b	0.250	0.380	0.010	0.015	
С	0.090	0.230	0.004	0.009	
D	2.900	3.100	0.114	0.122	
D1	1.700	1.900	0.067	0.075	
е	0.65	BSC	0.026 BSC		
E	2.900	3.100	0.114	0.122	
E1	4.750	5.050	0.187	0.199	
E2	1.450	1.650	0.057	0.065	
L	0.400	0.800	0.016	0.031	
θ	0°	6°	0°	6°	

- Body dimensions do not include mode flash or protrusion.
   This drawing is subject to change without notice.



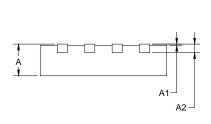
# **PACKAGE OUTLINE DIMENSIONS TDFN-3×3-8L**

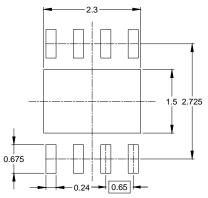




**BOTTOM VIEW** 

**TOP VIEW** 





**SIDE VIEW** 

RECOMMENDED LAND PATTERN (Unit: mm)

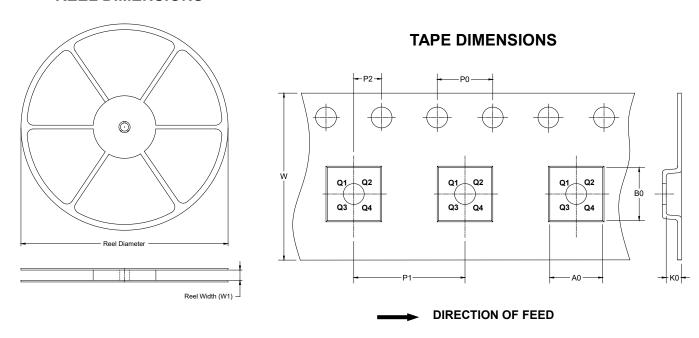
Symbol		nsions meters	Dimensions In Inches		
	MIN	MAX	MIN	MAX	
А	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
A2	0.203	REF	0.008 REF		
D	2.900	3.100	0.114	0.122	
D1	2.200	2.400	0.087	0.094	
Е	2.900	3.100	0.114	0.122	
E1	1.400	1.600	0.055 0.063		
k	0.200 MIN		0.008	MIN	
b	0.180	0.300	0.007	0.012	
е	0.650 TYP		0.026	TYP	
L	0.375	0.575	0.015 0.023		

NOTE: This drawing is subject to change without notice.



#### TAPE AND REEL INFORMATION

#### **REEL DIMENSIONS**

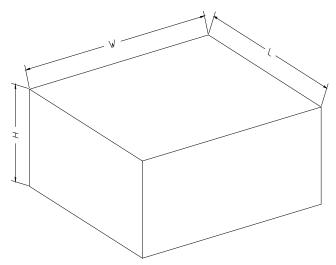


NOTE: The picture is only for reference. Please make the object as the standard.

#### **KEY PARAMETER LIST OF TAPE AND REEL**

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOIC-8	13″	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
MSOP-8 (Exposed Pad)	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
TDFN-3×3-8L	13"	12.4	3.35	3.35	1.13	4.0	8.0	2.0	12.0	Q1

#### **CARTON BOX DIMENSIONS**



NOTE: The picture is only for reference. Please make the object as the standard.

#### **KEY PARAMETER LIST OF CARTON BOX**

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5